



Material Content Data Sheet



Sales Product Name		BGA 735N16 E6327		Issued		2. August 2018		
MA#		MA001185690						
Package		PG-TSNP-16-1		Weight*		6.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.279	4.01	4.01	40083	40083
leadframe	non noble metal	zinc	7440-66-6	0.007	0.10		963	
	non noble metal	tin	7440-31-5	0.008	0.12		1203	
	non noble metal	chromium	7440-47-3	0.010	0.14		1444	
	non noble metal	copper	7440-50-8	3.327	47.76	48.12	477767	481377
wire	noble metal	gold	7440-57-5	0.076	1.09	1.09	10856	10856
encapsulation	organic material	carbon black	1333-86-4	0.014	0.20		1978	
	plastics	epoxy resin	-	0.399	5.74		57355	
	inorganic material	silicondioxide	60676-86-0	2.341	33.62	39.56	336220	395553
leadfinish	non noble metal	tin	7440-31-5	0.212	3.05	3.05	30458	30458
plating	noble metal	silver	7440-22-4	0.162	2.33	2.33	23266	23266
glue	plastics	epoxy resin	-	0.026	0.37		3681	
	noble metal	silver	7440-22-4	0.103	1.47	1.84	14726	18407
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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